

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 8 (canceled)

9 (currently amended) A semiconductor package with a heat sink structure with embedded electronic components, comprising:

 a substrate having a first surface and a second surface, the first surface being formed with a plurality of electrical connection pads thereon;

 at least one semiconductor chip mounted on and electrically connected to the first surface of the substrate;

 a heat sink having an upper surface and a lower surface, with the lower surface attached to the first surface of the substrate and formed with a plurality of recessed cavities thereon, allowing at least one electronic component with a plurality of electrodes to be embedded in at least one of the recessed cavities, wherein the lower surface of the heat sink is attached to the first surface of the substrate via the electrodes of the embedded electronic component electrically connected to the electrical connection pads on the substrate, and at least one through hole is formed through the first surface and the second surface of the heat sink to receive the at least one semiconductor chip to be received in at least one of the other recessed cavities; and

a resin compound filled in a space between the heat sink and the substrate;
and

 a plurality of conductive elements mounted on the second surface of the substrate for electrically connecting the semiconductor package to an external device.

10 (canceled)

11 (original) The semiconductor package of claim 9, wherein a continuous protruded portion is formed at the periphery on the lower surface of the heat sink.

12 (original) The semiconductor package of claim 9, wherein the electronic component is an active or passive component.

13 (canceled)

14 (original) The semiconductor package of claim 9, wherein the heat sink is made of a highly conductive and rigid material.